

AMENDMENTS TO THE SPECIFICATION:

Paragraph starting on line 22 of page 6 has been amended as follows:

For a tape-polishing method as shown in Fig. 2, a chuck 21 having a base plate 20 attached is rotated in the direction of ~~arrow RE~~ arrow R and polishing slurry of this invention is supplied to the surface of the base plate 20 through a nozzle 22. A contact roller 23 serves to push a polishing tape 26 against the surface of the base plate 20 while being rotated in the direction of arrow T. A porous tape of a woven or non-woven cloth may be used as the polishing tape 26. A tape having a polishing layer with abrading particles attached by means of a resin binder may also be used as the polishing tape 26.